


Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P194D1/P04836D1	NEW
	Applicant:	
	MOSTAFAZADEH	
Filing Date	Group	
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	1	6,261,864	7/17/01	Jung et al.			
	2	6,451,627	7/17/02	Coffman			
	3	6,306,685	10/23/01	Liu et al.			
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Foreign Patent or Published Foreign Patent Application

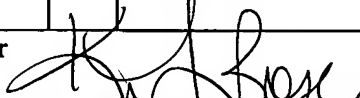
Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No



8/17/04

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	Applicant:	
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Filing Date	Group	
HEREWITH	UNASSIGNED	

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
KP	29	U.S. Patent Application No. 09/528,540, entitled "Leadless Packaging Process Using a Conductive Substrate", filed March 20, 2000, inventor(s): Bayan et al.
↓	30	U.S. Patent Application No. 09/698,784, entitled "Flip Chip Scale Package", filed October 26, 2000, inventor(s): Shahram Mostafazadeh
KP	31	U.S. Patent Application No. 09/698,736, entitled "Chip Scale Pin Array", filed October 26, 2000, inventor(s): Shahram Mostafazadeh
Examiner		
	Date Considered	8/17/04

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.